

MARKING DIAGRAMS

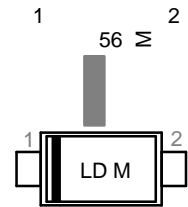


SOD-323
CASE 477



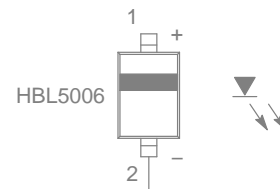
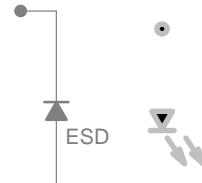
SOD-523
CASE 502

SOD-923
CASE 514AB



XX = Specific Device Code
M = Date Code

HBL5006



Apply heat sinking to pin 2

ORDERING INFORMATION

... .. 5 ...

HBL5006 Series

MAXIMUM RATINGS

Rating	Symbol	Value
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HBL5006 Series

ELECTRICAL CHARACTERISTICS (Unless otherwise noted: $T_A = 25^\circ\text{C}$)

Symbol	Characteristics	Package	Min	Typ	Max	Unit
V_{BR}	Breakdown Voltage: The minimum voltage across the device in or at the breakdown region. Measured at $I_{BR} = 1\text{ mA}$.	SOD-323	6.2	7.0		V
		SOD-523	6.2	7.0		
		SOD-923	6.2	7.0		
I_H	Holding Current: The minimum current required to maintain the device in the on-state.	SOD-323		25	40	mA
		SOD-523		25	40	
		SOD-923		25	40	
I_L						

HBL5006 Series

TYPICAL APPLICATION CIRCUIT

Typical Application Circuit for HBL5006

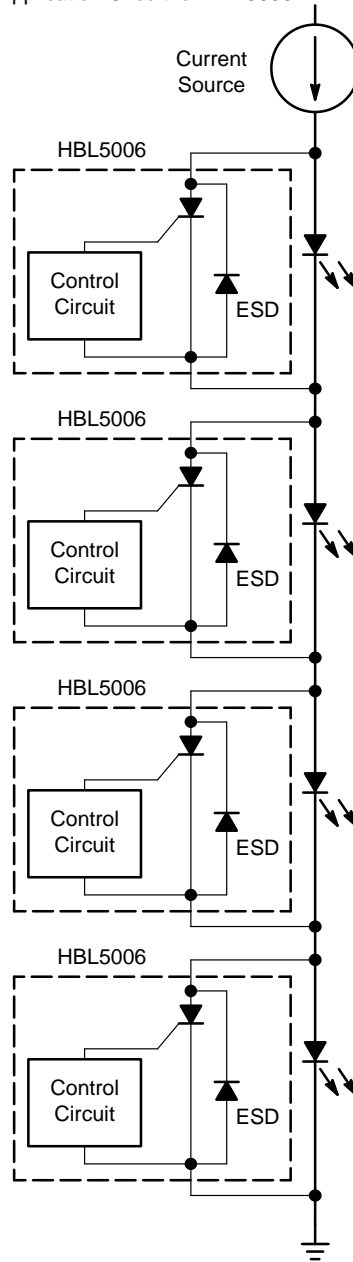


Figure 2. Typical Application Circuit

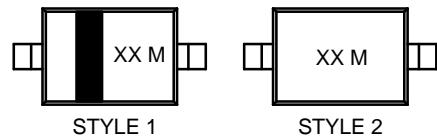
SOD-323 1.70x1.25x0.85
CASE 477
ISSUE K

DATE 11 MAR 2024

RECOMMENDED MOUNTING FOOTPRINT

*For additional

**GENERIC
MARKING DIAGRAM***

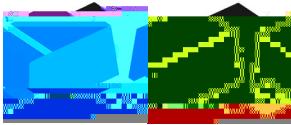


XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

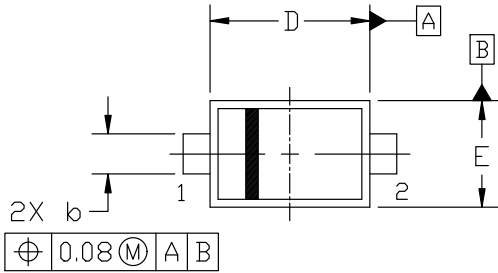
STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2:
NO POLARITY



CASE 502
ISSUE F

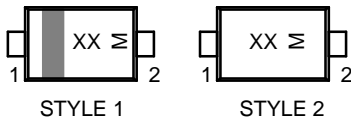
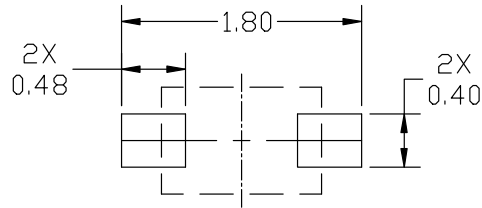
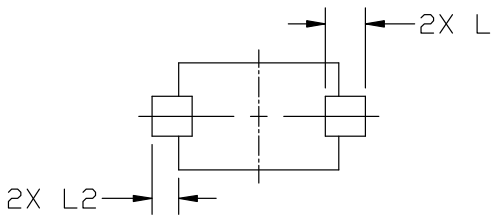
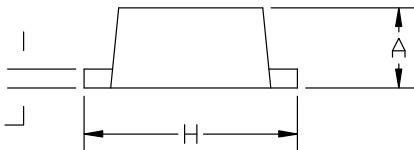
DATE 08 FEB 2024



2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

MILLIMETERS		
DIM	MIN.	NOM.
0.50	0.50	0.60

AND TOLERANCING PER ASME Y14.5M, 2



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M = Date Code

*For additional information

ing and Mounting Techniques
Reference manual, SOLDERRM/D.

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STYLE 1: PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2: NO POLARITY



c strategy and soldering
details, please download the [ON](#)
Semiconductor Soldering and Mount

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